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11. Thick film patterning by lift-off process using double-coated single photoresists, Yifeng Fu, Li-Lei Ye and Johan Liu, *Materials Letters* 76 (2012) 117–119.

12. Surface Characterisation of Oxygen Plasma Treated Electrospun Polyurethane Fibres and their interaction with Red Blood Cells, Carl Zandén, Marina Voinova, Julie Gold, Daniel Mörsdorf, Ingolf Bernhardt and Johan Liu, *European Polymer Journal* 48 (2012) 472–482.
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